



Document number
CCDA09:483
Date
2009-09-02
Remarks

Revision
A

Prepared by
SEM/CCMVALE Afrah Sadiq + 46 10 80 12250
Contents responsible if other than preparer

Approved by
SEM/CCMVALE Peter Lindeborg + 46 10 80 24 368

Receiver: Federal Communication Commission and
Certification and Engineering Bureau
Industry Canada

Application FFC ID: PY7A3880047,

IC: 4170B-A3880047

Type number: AAD-3880047-BV

Statement of Hardware Change

Valid for: Permissive Change Class II on Hardware-B for AAD-3880047-BV

Hardware-B changes:

1.
The SIM card holder has been replaced to improve the communication link between control circuit's on the main PCB and the SIM card.
2.
The antenna radiated performance is improved.

These changes do not affect Bluetooth performance. The Bluetooth test report (report no. 1-1065-33-04/09, dated 2009-06-25) apply for Hardware-B

Best Regards,

Peter Lindeborg

Technical Manager – EMF and Safety

Sony Ericsson Mobile Communications AB - Lund

Sony Ericsson Mobile Communications AB

Postadress • Mail
SE-221 88 Lund
Sweden

Besöksadress • Office address
Nya Vattentornet
Lund

Styrelsens säte: Lund
Registered office: Lund
Telefon • Telephone
Nat 046-19 40 00
Int +46 46 19 40 00

Momsnr • V.A.T.No: SE556615665801
Organisationsnr • Reg No: 556615-6658
Telefax • Telefax
Nat 046-19 41 00
Int +46 46 19 41 00

Prepared (also subject responsible if other)

No.

SEMC/CCMVALG Johan Wedinders Nordlöf

Approved

Checked

Date

Rev

Reference

SEMC/CCMVAL Anders Nordlöf

2009-07-14

A

HW change description for

MS type:	AAD-388046-BV	AAD-388047-BV
Supporting:	GSM 850/900/1800/1900 FDD I/VIII	GSM 850/900/1800/1900 FDD I/II/V
Market name:	Yari, U100i	Yari, U100a
FCC id:	PY7A3880046	PY7A3880047
IC id:	4170B-A3880046	4170B-A3880047
Hardware:	A to B	A to B

1 Background

The following changes have been done between HW A and B for MS type AAD-388046-BV and AAD-388047-BV:

- Filter has changed value to improve performance for Fast transient.
Component Z2400 changed to Sony Ericsson part number 1225-1423
- 2 Inductors added to improve Current Clamp performance. Sony Ericsson part number 1000-2609
- Conducted gasket added between Combi Flex and hinge to improve RSE performance.
- Increased ground plane on Combi Flex to reduce SAR level.
- Improved SIM lid (added connection via screw to ground plane)
- Changed mechanics for the SIM interface. (SIM lid is new and base carrier is changed so that SIM card is inserted from the side.)

Prepared (also subject responsible if other)

No.

SEMC/CCMVALG Johan Wedinders Nordlöf

Approved

Checked

Date

Rev

Reference

SEMC/CCMVAL Anders Nordlöf

2009-07-14

A

2 Re-testing consequences

2.1 Conducted re-testing

2.1.1 3GPP TS 51.010 Requirement

TC	Name
27.11.x and 27.17.x	SIM electrical and logical

ETSI TS 102 230

TC	Name
5.x, 6.x, 7.x and 8x	SIM electrical and logical

2.2 Radiated and EMC testing

- FCC Part 22/24 Radiated Power
- FCC Part 22/24 Radiated Emission
- FCC Part 22/24 Conductive Output Power
- OTA (Over The Air) in all bands
- 12.2.1 Radiated spurious emissions - MS allocated a channel
- 12.2.2 Radiated spurious emissions - MS in idle mod
- ESD